

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040051763"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 11:40
S2	265	(piezo\$3electric) with (film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 adj modulus))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:43
S3	23	perovskite and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 11:42
S4	1	((piezo\$3electric) with (film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 adj modulus))) same perovskite	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 11:44
S5	451	(piezo\$3electric) with (film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:43
S6	57	(piezo\$3electric) with (film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus)) with (metal oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:00
S7	402	(piezo\$3electric) with (film layer\$3 substrate) with (tce (thermal adj expansion) (heat adj expansion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:33
S8	9	((piezo\$3electric) with (film layer\$3 substrate) with (tce (thermal adj expansion) (heat adj expansion))) same ink\$3jet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:36

S9	37	((piezo\$3electric) with (film layer\$3 substrate) with (tce (thermal adj expansion) (heat adj expansion))) and ink\$3jet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:47
S10	20287	(film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus)) with (stress near3 reduc\$4 (young\$3 adj modulus))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 14:44
S11	22	(film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus)) with (stress near3 reduc\$4 (young\$3 adj modulus)) same perovskite	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:30
S12	672	310/346,364.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:30
S13	46812	(film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:35
S14	31	S12 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:35
S15	2856	347/68-72.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:35
S16	117	S13 and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:35

S17	350417	(film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus) thermal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:36
S18	429	S15 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:36
S19	16289	S18 and perovskite pzt	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:36
S20	239	S18 and (perovskite pzt)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:36
S21	15735	(film layer\$3 substrate) with (stress near3 reduc\$4 (young\$3 modulus) thermal) same crack\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:36
S22	21	S15 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:37
S23	1573	(tce (thermal adj expansion) (heat adj expansion)) with (piezoelectric perovskite pzt)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:48
S24	112	S15 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:48

S25	287	(tce (thermal adj expansion) (heat adj expansion)) with (piezoelectric perovskite pzt) with (stress reduc\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:49
S26	34	S15 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/18 15:49
S27	1	c\$2axis adj oriented adj rate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/19 15:35